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US Department Of Commerce ec

Docket: HSJ9-2006-0065US1

Patent & Trademark Office

12-26-06

To the Honorable Commissioner of Patents and Trademarks: Please record the attached original documents or copy thereof.

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1. Name of conveying party(ies):

Hieu Lam
Patrick Rush Webb
Yi Zheng

Additional name(s) of conveying party(ies) attached __Yes XX No

2. Name and address of receiving party(ies):

Name: **Hitachi Global Storage Technologies Netherlands B.V.**

Street Address:
Locatellikade 1
Parnassustoren
1076 AZ Amsterdam
The Netherlands

Additional name(s) & address(es) attached? __Yes XX No

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3. Nature of conveyance:

XX Assignment Execution Date: **11/8/2006**

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4. Application number(s) or patent number(s):

If this document is being filed together with a new application, the execution date of the application is:____________________

A. Patent Application No.(s)
11/595,764 filed 11/10/2006

B. Patent No.(s)

Additional numbers attached? __Yes XX No

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5. Name and address of party to whom correspondence concerning document should be mailed:

Name: Hitachi Global Storage Technologies
Internal Address: **Intellectual Property Law**
Street Address: 5600 Cottle Road, Dept. NHGB/014-2,
San Jose, California 95193

6. Total Number of applications and patents involved: **One**

7. Total fee (37 CFR 3.41)......$ **40.00**
__ Enclosed
XX Authorized to be charged to deposit account

8. Deposit Account Number: **50-2587**

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9. Statement and signature.
To the best of my knowledge and belief, the foregoing information is true and correct and any attached copy is a true copy of the original document.

12/29/2006 LMUELLER 00000019 502587 11595764
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12/22/2006
Date

D'Arcy H. Lorimer

Total number of pages including cover sheet, attachments, and document: / 2 /

ASSIGNMENT

Whereas, we

INVENTOR AND CITY

(1) **Hieu Lam of Milpitas, CA.;**
(2) **Patrick Rush Webb of San Jose, CA.;**
(3) **Yi Zheng of San Ramon, CA.; and,**

have invented certain improvements in

TITLE

METAL CAPPED SEED LAYERS FOR THE FABRICATION OF WRAP AROUND AND TRAILING SHIELDS

DATES THAT INVENTORS SIGNED THE

and executed, respectively, a United States patent application therefore on
(1) 11/08/2006 (2) 11/8/2006 (3) 11/7/2006

Whereas, **HITACHI GLOBAL STORAGE TECHNOLOGIES NETHERLANDS B.V.**, having a place of business at Locatellikade 1, Parnassustoren, 1076 AZ Amsterdam, The Netherlands (hereinafter called HITACHI), desires to acquire the entire right, title and interest in the said application and invention, and to any United States and foreign patents to be obtained therefore;

Now therefore, for a valuable consideration, receipt whereof is hereby acknowledged, we, the above named, hereby sell, assign, and transfer to HITACHI, its successors and assigns, the entire right, title and interest in the said application and invention therein disclosed for the United States and foreign countries, and all rights of priority resulting from the filing of said United States application, and we request the Commissioner of Patents to issue any Letters Patent granted upon the inventions set forth in said application to HITACHI, its successors and assigns; and we hereby agree that HITACHI may apply for foreign Letters Patent on said invention and we will execute all papers necessary in connection with the United States and foreign applications when called upon to do so by HITACHI.

Signed

CITY (1) at San Jose
DATE on 11/08, 2006,
Hieu Lam SIGNATURE INVENTOR

CITY (2) at San Jose
DATE on 11/8, 2006,
Patrick Rush Webb SIGNATURE INVENTOR

CITY (3) at San Jose
DATE on 11/7, 2006,
Yi Zheng SIGNATURE INVENTOR